

Solder Wire Sn99.3/Cu0.7 No-Clean with 2.2% Flux Core 8oz Spool

Product Highlights

No-Clean Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board.

2.2% flux core

Halogen content: None

RoHS 3 and REACH compliant

Specifications

| | |
|----------------------|--------------------|
| Alloy: | Sn99.3/Cu0.7 |
| Wire Diameter: | 0.015" (0.38mm) |
| Flux Type: | No-Clean Synthetic |
| Flux Classification: | ROL0 |
| Melting Point: | 227°C (441°F) |
| Packaging: | 8 oz spool |
| Shelf Life: | >60 months |



Test Results

| Test J-STD-004 or other requirements as stated | Test Requirement | Result |
|--|--|--|
| Copper Mirror | IPC-TM-650: 2.3.32 | L: No breakthrough |
| Corrosion | IPC-TM-650: 2.6.15 | L: No corrosion |
| Quantitative Halides | IPC-TM-650: 2.3.28.1 | L: <0.05% |
| Electrochemical Migration | IPC-TM-650: 2.6.14.1 | L: <1 decade drop (No-clean) |
| Surface Insulation Resistance 85°C, 85% RH @ 168 Hours | IPC-TM-650: 2.6.3.7 | L: ≥100MΩ (No-clean) |
| Visual | IPC-TM-650: 3.4.2.5 | Clear and free from precipitation |
| Conflict Minerals Compliance | Electronic Industry Citizenship Coalition (EICC) | Compliant |
| REACH Compliance | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |

Conforms to the following Industry Standards:

| | |
|---|-----|
| J-STD-004B, Amendment 1 (Solder Fluxes): | Yes |
| J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): | Yes |
| RoHS 3 Directive (EU) 2015/863: | Yes |

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